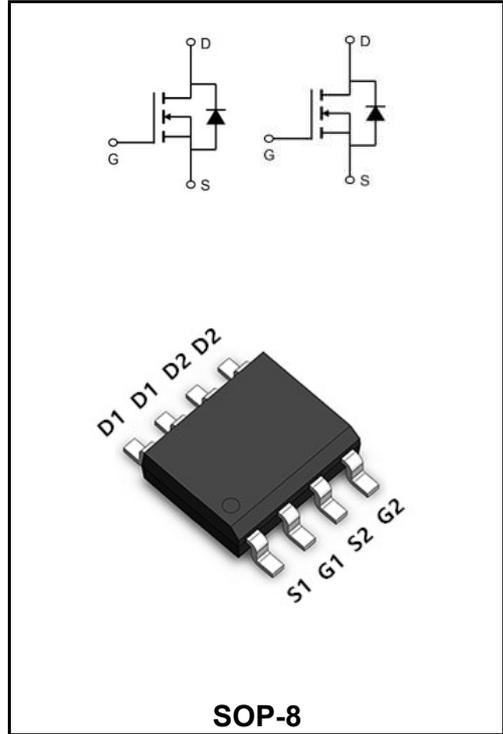


**60V N+N-CHANNEL ENHANCEMENT MODE MOSFET**

**MAIN CHARACTERISTICS**

<b>I<sub>D</sub></b>	7.2A
<b>V<sub>DSS</sub></b>	60V
<b>R<sub>DS(on)-typ</sub>(@V<sub>GS</sub>=10V)</b>	< 35mΩ( <b>Type:28 mΩ</b> )



**Application**

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFW6946S	SOP-8	YFW 6946S XXXXX	3000PCS/Tape

**Maximum Ratings at Tc=25°C unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	<b>V<sub>DS</sub></b>	60	<b>V</b>
Gate - Source Voltage	<b>V<sub>GS</sub></b>	±20	<b>V</b>
Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> @T <sub>A</sub> =25°C	<b>I<sub>D</sub></b>	7.2	<b>A</b>
Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup> @T <sub>A</sub> =70°C	<b>I<sub>D</sub></b>	4.8	<b>A</b>
Pulsed Drain Current <sup>2</sup>	<b>I<sub>DM</sub></b>	14.6	<b>A</b>
Single Pulse Avalanche Energy <sup>3</sup>	<b>E<sub>AS</sub></b>	21.5	<b>mJ</b>
Avalanche Current	<b>I<sub>AS</sub></b>	20.6	<b>A</b>
Total Power Dissipation <sup>4</sup> @T <sub>A</sub> =25°C	<b>P<sub>D</sub></b>	1.2	<b>W</b>
Storage Temperature Range	<b>T<sub>STG</sub></b>	-55 to +150	<b>°C</b>
Operating Junction Temperature Range	<b>T<sub>J</sub></b>	-55 to +150	<b>°C</b>
Thermal Resistance Junction-ambient <sup>1</sup>	<b>R<sub>θJA</sub></b>	62.5	<b>°C/W</b>
Thermal Resistance Junction-Case <sup>1</sup>	<b>R<sub>θJC</sub></b>	36	<b>°C/W</b>

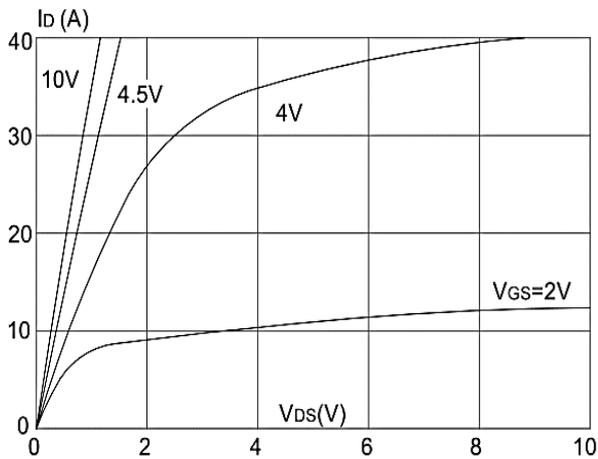
**Maximum Ratings at Tc=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	<b>V(BR)DSS</b>	60	65	-	<b>V</b>
Zero Gate Voltage Drain Current	$V_{DS}=60V, V_{GS}=0V$	<b>I<sub>DSS</sub></b>	-	-	1.0	<b>μA</b>
Gate to Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	<b>I<sub>GSS</sub></b>	-	-	±100	<b>nA</b>
Gate -Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	<b>V<sub>GS(th)</sub></b>	1.0	1.6	2.5	<b>V</b>
Static Drain-Source On-Resistance note3	$V_{GS}=10V, I_D=10A$	<b>R<sub>DS(ON)</sub></b>	-	28	35	<b>mΩ</b>
	$V_{GS}=4.5V, I_D=5A$		-	33	45	<b>mΩ</b>
Input Capacitance	$V_{DS}=25V$ $V_{GS}=0V$ $f=1.0MHz$	<b>C<sub>iss</sub></b>	-	1148	-	<b>μF</b>
Output Capacitance		<b>C<sub>oss</sub></b>	-	58.5	-	
Reverse Transfer Capacitance		<b>C<sub>rss</sub></b>	-	49.4	-	
Total Gate Charge	$V_{DS}=30V$ $I_D=10A$ $V_{GS}=10V$	<b>Q<sub>g</sub></b>	-	20.3	-	<b>nC</b>
Gate-Source Charge		<b>Q<sub>gs</sub></b>	-	3.7	-	
Gate-Drain("Miller") Charge		<b>Q<sub>gd</sub></b>	-	5.3	-	
Turn-on delay time	$V_{DS}=30V$ $I_D=20A$ $R_{GEN}=1.8\Omega$ $V_{GS}=10V$	<b>t<sub>d(on)</sub></b>	-	7.6	-	<b>ns</b>
Turn-on Rise Time		<b>T<sub>r</sub></b>	-	20	-	
Turn-Off Delay Time		<b>t<sub>d(OFF)</sub></b>	-	15	-	
Turn-Off Fall Time		<b>t<sub>f</sub></b>	-	24	-	
Maximum Continuous Drain to Source Diode Forward Current		<b>I<sub>S</sub></b>	-	-	20	<b>A</b>
Maximum Pulsed Drain to Source Diode Forward Current		<b>I<sub>SM</sub></b>	-	-	80	<b>A</b>
Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=20A$	<b>V<sub>SD</sub></b>	-	-	1.2	<b>V</b>
Body Diode Reverse Recovery Time	$I_F=20A, di/dt=100A/\mu s$	<b>t<sub>rr</sub></b>	-	29	-	<b>ns</b>
Body Diode Reverse Recovery Charge		<b>Q<sub>rr</sub></b>	-	43	-	<b>nC</b>

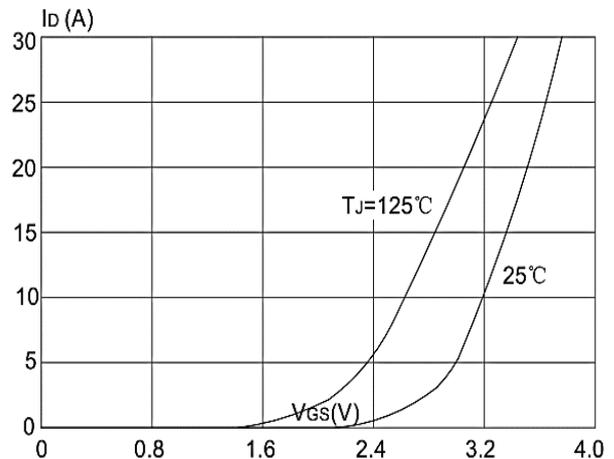
**Notes:**

- 1、 Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- 2、 EAS condition : T<sub>J</sub> =25°C, V<sub>DD</sub> =30V, V<sub>G</sub> =10V, L=0.5mH, R<sub>G</sub>=25Ω, I<sub>AS</sub> =8.5A
- 3、 Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

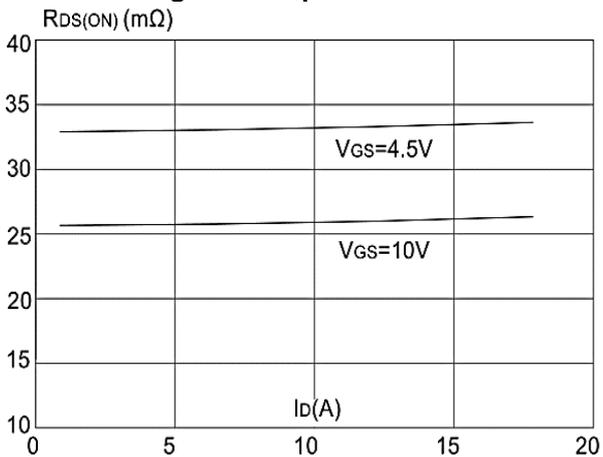
**Ratings and Characteristic Curves**



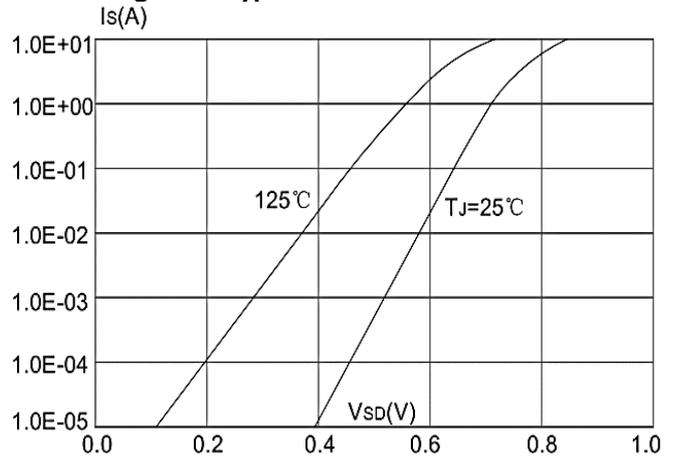
**Figure 1: Output Characteristics**



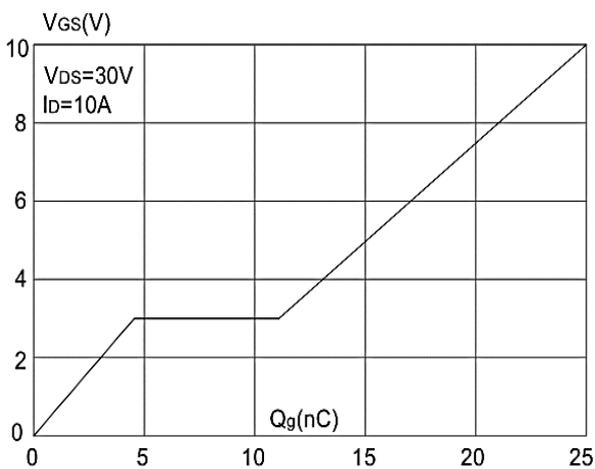
**Figure 2: Typical Transfer Characteristics**



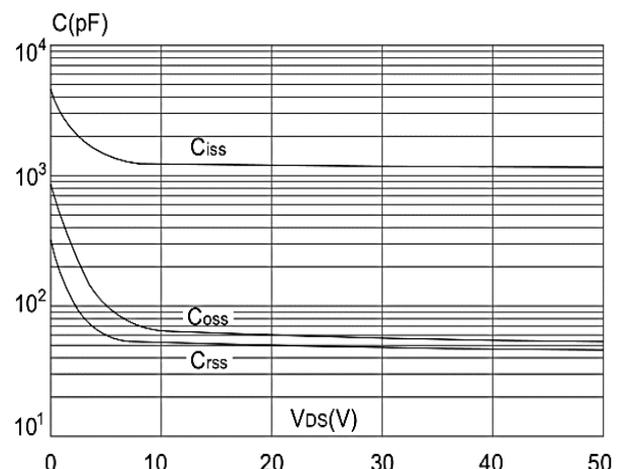
**Figure 3: On-resistance vs. Drain Current**



**Figure 4: Body Diode Characteristics**

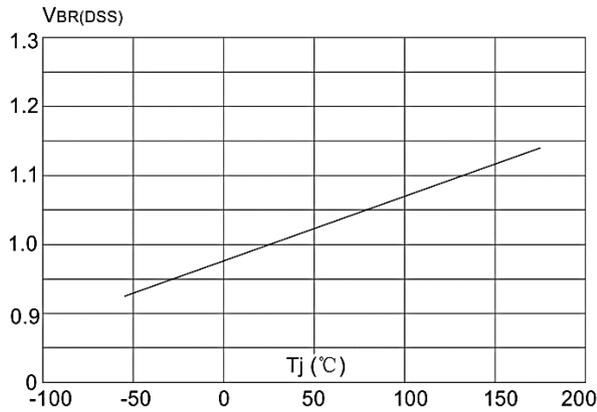


**Figure 5: Gate Charge Characteristics**

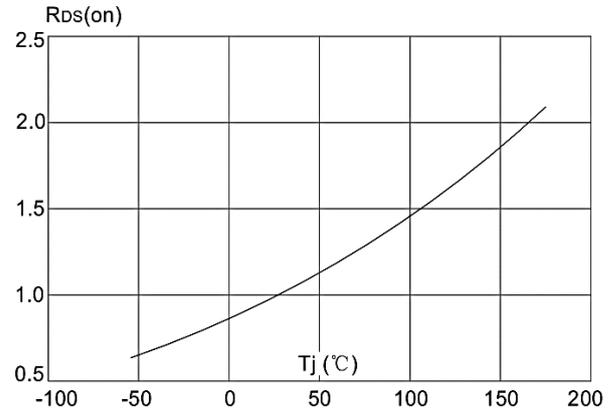


**Figure 6: Capacitance Characteristics**

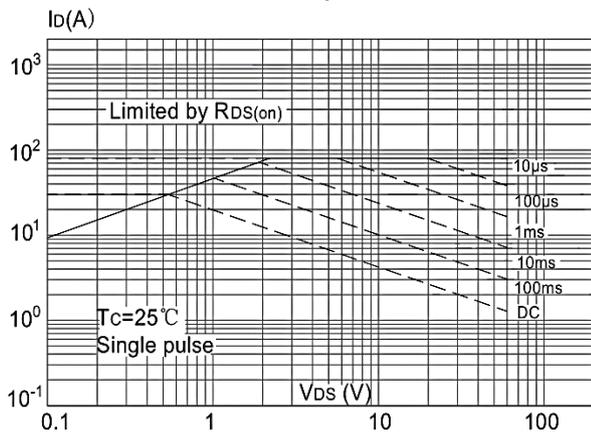
**Ratings and Characteristic Curves**



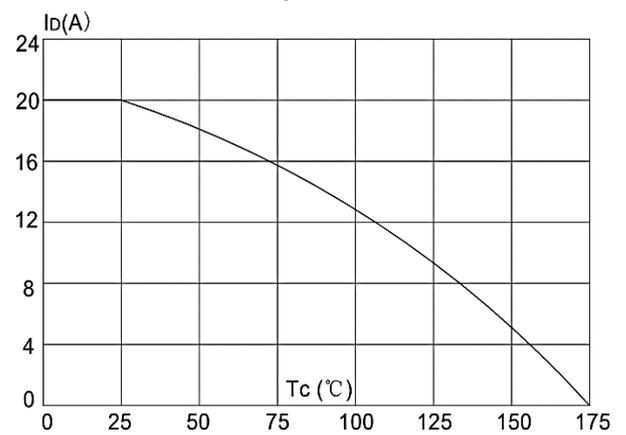
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



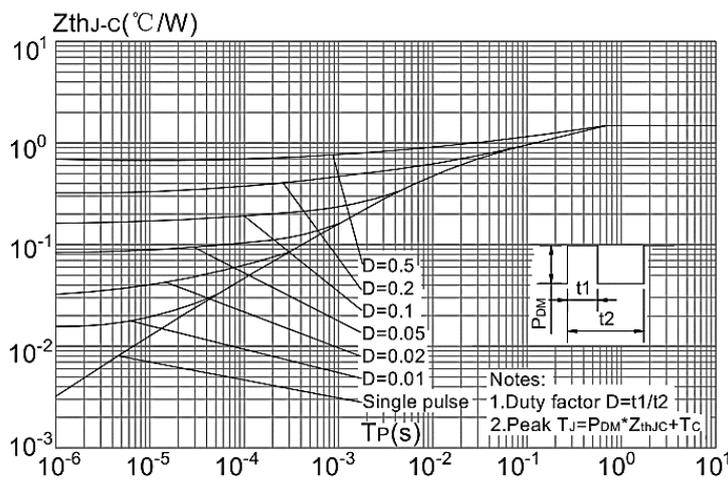
**Figure 8: Normalized on Resistance vs. Junction Temperature**



**Figure 9: Maximum Safe Operating Area vs. Case Temperature**

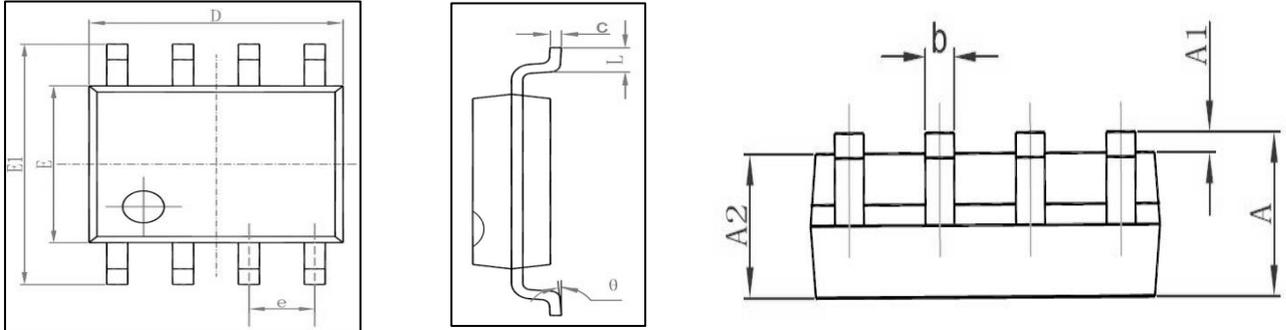


**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**

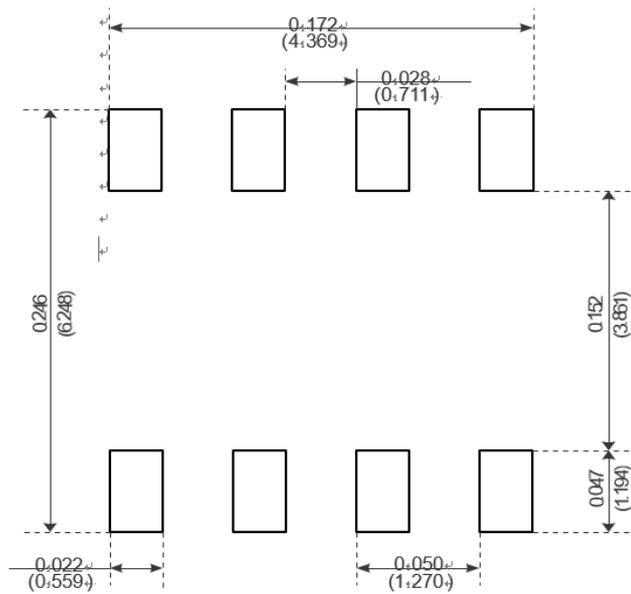


**Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case**

**SOP-8**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Recommended Minimum Pads